

## N-Channel 100 V (D-S) MOSFET



**RoHS**  
COMPLIANT

### PRODUCT SUMMARY

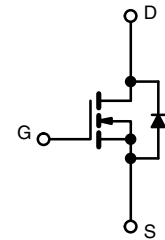
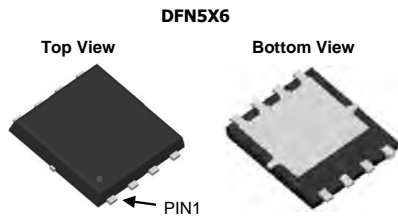
| V <sub>DS</sub> (V) | R <sub>DS(on)</sub> (Ω)          | I <sub>D</sub> (A) <sup>a, d</sup> | Q <sub>g</sub> (Typ.) |
|---------------------|----------------------------------|------------------------------------|-----------------------|
| 100                 | 0.0056 at V <sub>GS</sub> = 10 V | 112                                | 120nC                 |

### FEATURES

- TrenchFET IIPower MOSFET
- 100 % Rgand UIS Tested

### APPLICATIONS

- Synchronous rectification
- Primary side switch
- DC/DC converters
- OR-ing
- Power supplies
- Motor drive control
- Battery and load switch



N-Channel MOSFET

### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub> = 25 °C, unless otherwise noted)

| PARAMETER   | SYMBOL                            | LIMIT                  | UNIT                 |
|---|-----------------------------------|------------------------|----------------------|
| Drain-source voltage                                      | V <sub>DS</sub>                   | 100                    | V                    |
| Gate-source voltage                                       | V <sub>GS</sub>                   | ± 20                   |                      |
| Continuous drain current (T <sub>J</sub> = 150 °C)        | I <sub>D</sub>                    | T <sub>C</sub> = 25 °C | 112 <sup>a</sup>     |
|   |                                   | T <sub>C</sub> = 70 °C | 94.2                 |
|   |                                   | T <sub>A</sub> = 25 °C | 40.5 <sup>b, c</sup> |
|   |                                   | T <sub>A</sub> = 70 °C | 24.2 <sup>b, c</sup> |
| Pulsed drain current (t = 100 μs)                         | I <sub>DM</sub>                   | 448                    | A                    |
| Continuous source-drain diode current                     | I <sub>S</sub>                    | T <sub>C</sub> = 25 °C | 112 <sup>a</sup>     |
|   |                                   | T <sub>A</sub> = 25 °C | 7.3 <sup>b, c</sup>  |
| Single pulse avalanche current                            | I <sub>AS</sub>                   | 73                     |                      |
| Single pulse avalanche energy                             | E <sub>AS</sub>                   | 125                    | mJ                   |
| Maximum power dissipation                                 | P <sub>D</sub>                    | T <sub>C</sub> = 25 °C | 185                  |
|   |                                   | T <sub>C</sub> = 70 °C | 115                  |
|   |                                   | T <sub>A</sub> = 25 °C | 6.25 <sup>b, c</sup> |
|   |                                   | T <sub>A</sub> = 70 °C | 3.5 <sup>b, c</sup>  |
| Operating junction and storage temperature range          | T <sub>J</sub> , T <sub>stg</sub> | -55 to +150            | °C                   |
| Soldering recommendations (peak temperature) <sup>c</sup> |                                   | 260                    |                      |

### THERMAL RESISTANCE RATINGS

| PARAMETER                                | SYMBOL            | TYPICAL | MAXIMUM | UNIT |
|--|-------------------|---------|---------|------|
| Maximum junction-to-ambient <sup>b</sup> | R <sub>thJA</sub> | 13      | 22      | °C/W |
| Maximum junction-to-case (drain)         | R <sub>thJC</sub> | 0.7     | 1       |      |
| Maximum junction-to-case (source)        | R <sub>thJC</sub> | 1.0     | 1.4     |      |

Notes:

- Based on T<sub>C</sub> = 25 °C.
- Surface mounted on 1" x 1" FR4 board.
- t = 10 s.
- Calculated based on maximum junction temperature.

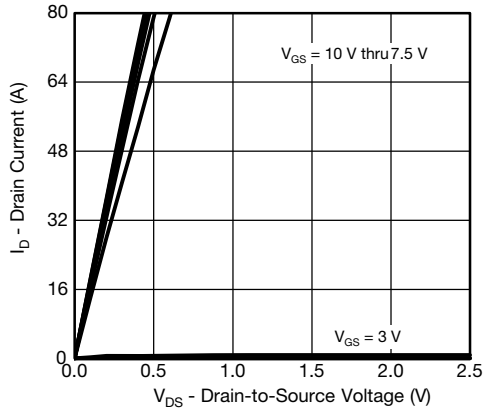
| <b>SPECIFICATIONS</b> ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted) |                         |   |      |        |        |                      |
|--|-------------------------|---|------|--------|--------|----------------------|
| PARAMETER  | SYMBOL                  | TEST CONDITIONS   | MIN. | TYP.   | MAX.   | UNIT                 |
| <b>Static</b>  |                         |   |      |        |        |                      |
| Drain-source breakdown voltage   | $V_{DS}$                | $V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$   | 100  | -      | -      | V                    |
| $V_{DS}$ temperature coefficient   | $\Delta V_{DS}/T_J$     | $I_D = 250\text{ }\mu\text{A}$  | -    | 56     | -      | mV/ $^\circ\text{C}$ |
| $V_{GS(th)}$ temperature coefficient   | $\Delta V_{GS(th)}/T_J$ | $I_D = 250\text{ }\mu\text{A}$  | -    | -6     | -      |                      |
| Gate-source threshold voltage  | $V_{GS(th)}$            | $V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$   | 2    | -      | 4      | V                    |
| Gate-source leakage  | $I_{GSS}$               | $V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$   | -    | -      | 100    | nA                   |
| Zero gate voltage drain current  | $I_{DSS}$               | $V_{DS} = 80\text{ V}, V_{GS} = 0\text{ V}$   | -    | -      | 1      | $\mu\text{A}$        |
|  |                         | $V_{DS} = 80\text{ V}, V_{GS} = 0\text{ V}, T_J = 70\text{ }^\circ\text{C}$   | -    | -      | 10     |                      |
| On-state drain current <sup>a</sup>  | $I_{D(on)}$             | $V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$  | 112  | -      | -      | A                    |
| Drain-source on-state resistance <sup>a</sup>                                      | $R_{DS(on)}$            | $V_{GS} = 10\text{ V}, I_D = 20\text{ A}$   | -    | 0.0056 | 0.0065 | $\Omega$             |
| Forward transconductance <sup>a</sup>  | $g_{fs}$                | $V_{DS} = 10\text{ V}, I_D = 20\text{ A}$   | -    | 66     | -      | S                    |
| <b>Dynamic <sup>b</sup></b>  |                         |   |      |        |        |                      |
| Input capacitance  | $C_{iss}$               | $V_{DS} = 50\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$   | -    | 6505   | -      | $\mu\text{F}$        |
| Output capacitance   | $C_{oss}$               |   | -    | 1470   | -      |                      |
| Reverse transfer capacitance   | $C_{rss}$               |   | -    | 172    | -      |                      |
| Total gate charge  | $Q_g$                   | $V_{DS} = 50\text{ V}, V_{GS} = 10\text{ V}, I_D = 20\text{ A}$   | -    | 120    | -      | nC                   |
| Gate-source charge   | $Q_{gs}$                |   | -    | 12     | -      |                      |
| Gate-drain charge  | $Q_{gd}$                |   | -    | 9      | -      |                      |
| Output charge  | $Q_{oss}$               | $V_{DS} = 50\text{ V}, V_{GS} = 0\text{ V}$   | -    | 63     | 110    |                      |
| Gate resistance  | $R_g$                   | $f = 1\text{ MHz}$  | 0.4  | 1      | 2      | $\Omega$             |
| Turn-on delay time   | $t_{d(on)}$             | $V_{DD} = 50\text{ V}, R_L = 2.5\text{ }\Omega, I_D \cong 20\text{ A},$<br>$V_{GEN} = 10\text{ V}, R_g = 1\text{ }\Omega$ | -    | 15     | -      | ns                   |
| Rise time  | $t_r$                   |   | -    | 19     | -      |                      |
| Turn-off delay time  | $t_{d(off)}$            |   | -    | 45     | -      |                      |
| Fall time  | $t_f$                   |   | -    | 10     | -      |                      |
| <b>Drain-Source Body Diode Characteristics</b>                                     |                         |   |      |        |        |                      |
| Continuous source-drain diode current  | $I_S$                   | $T_C = 25\text{ }^\circ\text{C}$  | -    | -      | 112    | A                    |
| Pulse diode forward current ( $t_p = 100\text{ }\mu\text{s}$ )                     | $I_{SM}$                |   | -    | -      | 448    |                      |
| Body diode voltage   | $V_{SD}$                | $I_S = 5\text{ A}, V_{GS} = 0\text{ V}$   | -    | 0.7    | 1.2    | V                    |
| Body diode reverse recovery time   | $t_{rr}$                | $I_F = 20\text{ A}, di/dt = 100\text{ A}/\mu\text{s}, T_J = 25\text{ }^\circ\text{C}$                                     | -    | 53     | 110    | ns                   |
| Body diode reverse recovery charge   | $Q_{rr}$                |   | -    | 77     | 123    | nC                   |
| Reverse recovery fall time   | $t_a$                   |   | -    | 25     | -      | ns                   |
| Reverse recovery rise time   | $t_b$                   |   | -    | 21     | -      |                      |

**Notes**

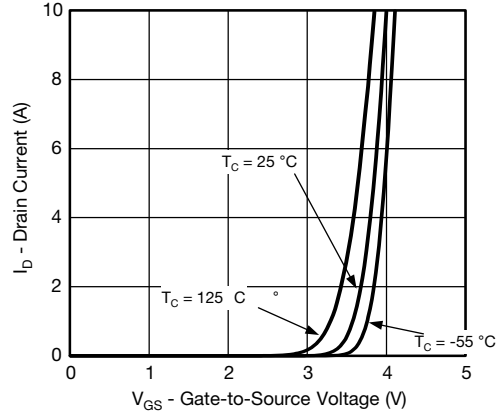
- a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

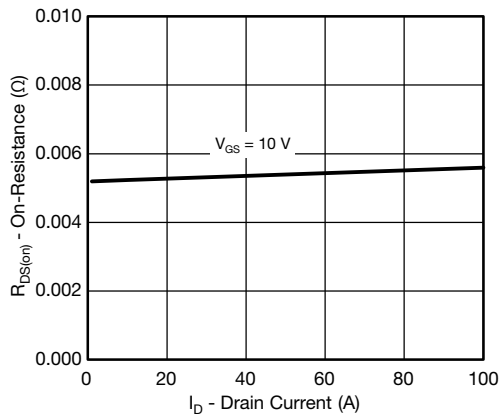
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



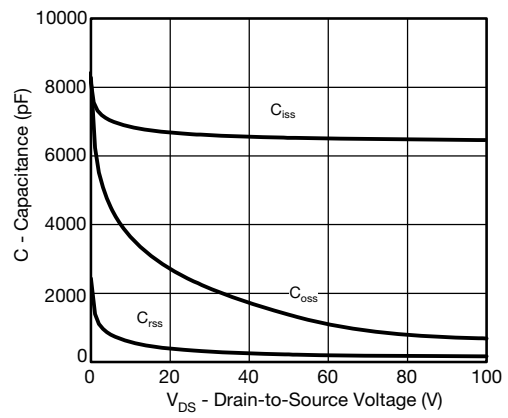
**Output Characteristics**



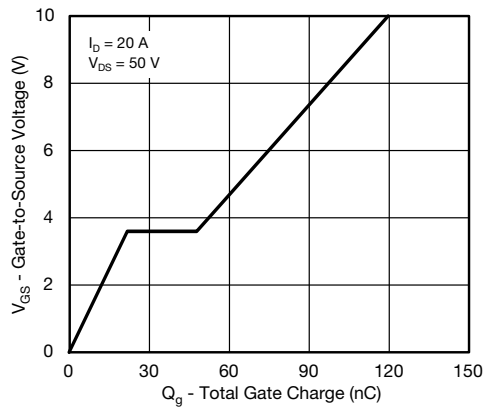
**Transfer Characteristics**



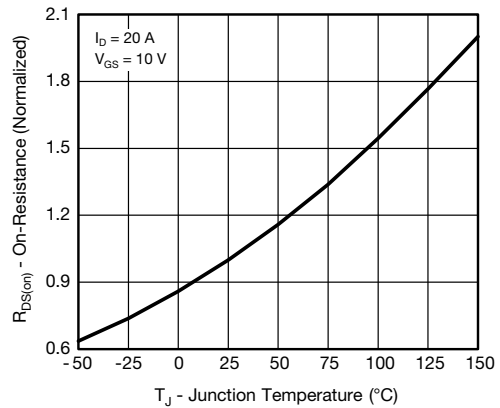
**On-Resistance vs. Drain Current and Gate Voltage**



**Capacitance**

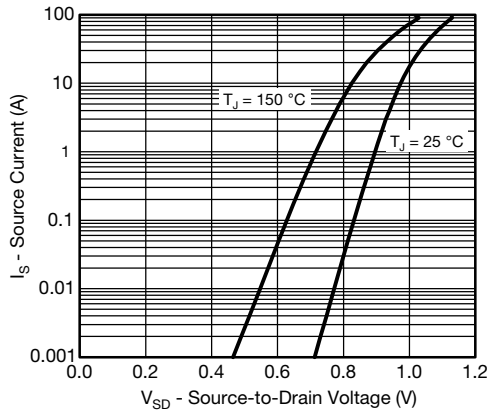


**Gate Charge**

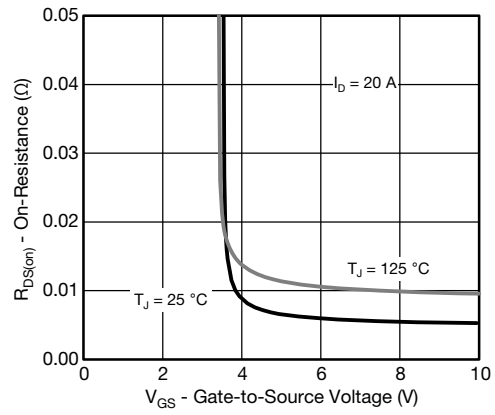


**On-Resistance vs. Junction Temperature**

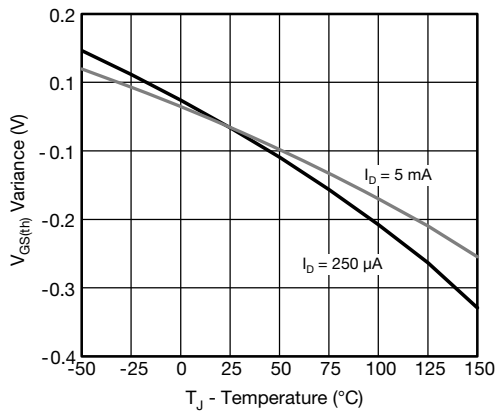
**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



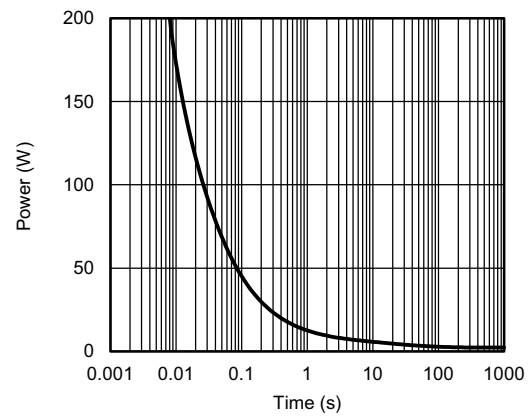
**Source-Drain Diode Forward Voltage**



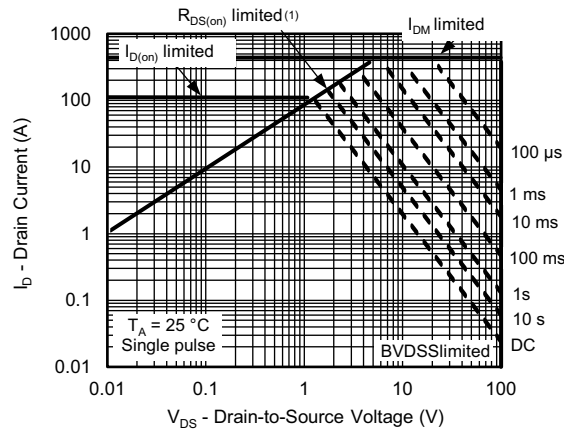
**Threshold Voltage**



**On-Resistance vs. Gate-to-Source Voltage**



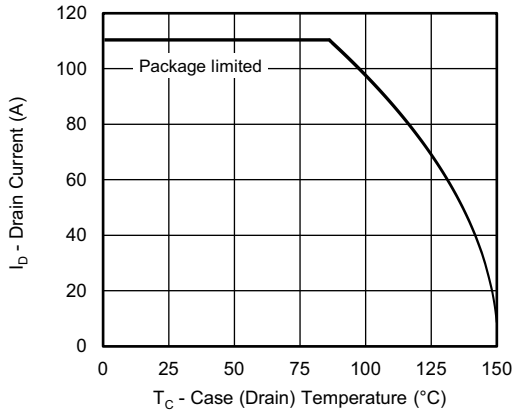
**Single Pulse Power, Junction-to-Ambient**



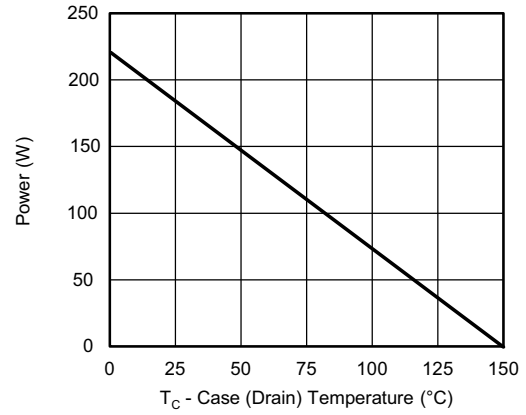
(1)  $V_{GS} >$  minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified

**Safe Operating Area, Junction-to-Ambient**

**TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



**Current Derating <sup>a</sup>**

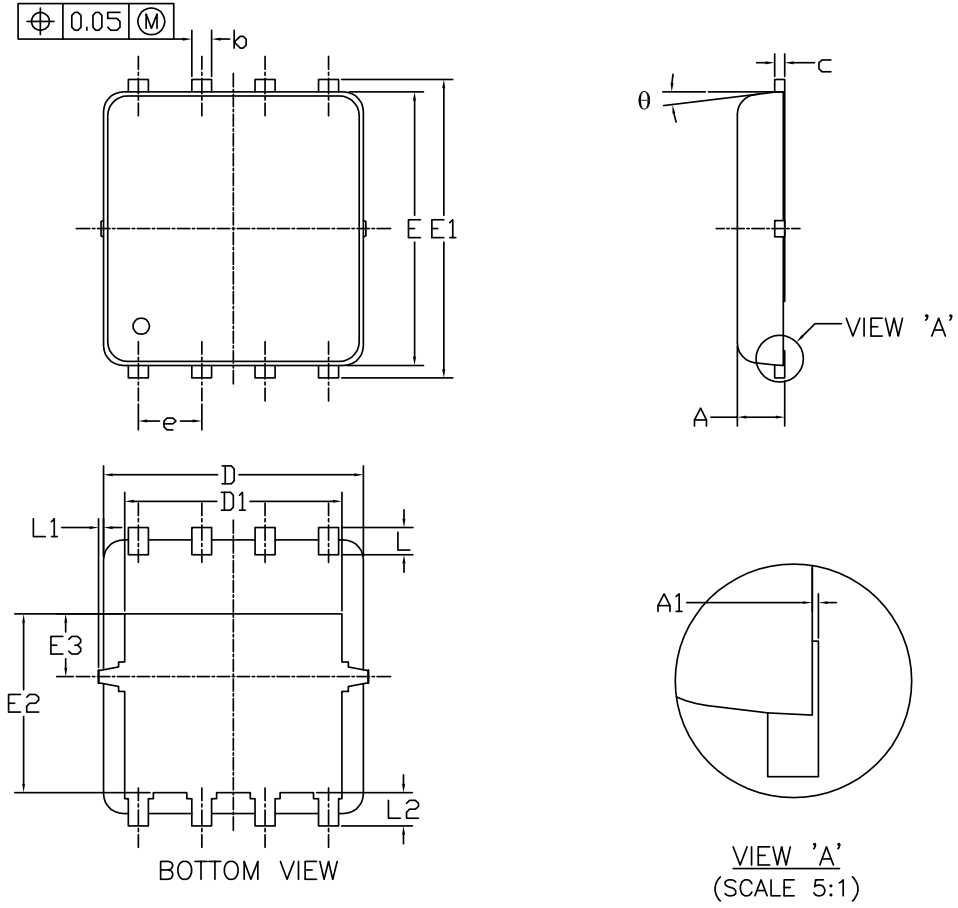


**Power, Junction-to-Case**

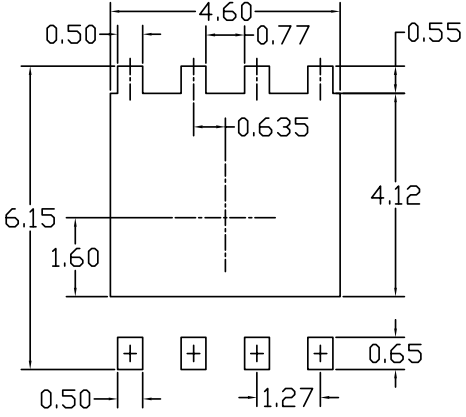
**Note**

- a. The power dissipation  $P_D$  is based on  $T_J$  max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit

DFN5x6\_8L\_EP1\_P PACKAGE OUTLIN



RECOMMENDED LAND PATTERN



| SYMBOLS  | DIMENSIONS IN MILLIMETERS |       |       | DIMENSIONS IN INCHES |       |       |
|----------|---------------------------|-------|-------|----------------------|-------|-------|
|          | MIN                       | NOM   | MAX   | MIN                  | NOM   | MAX   |
| A        | 0.85                      | 0.95  | 1.00  | 0.033                | 0.037 | 0.039 |
| A1       | 0.00                      | ---   | 0.05  | 0.000                | ---   | 0.002 |
| b        | 0.30                      | 0.40  | 0.50  | 0.012                | 0.016 | 0.020 |
| c        | 0.15                      | 0.20  | 0.25  | 0.006                | 0.008 | 0.010 |
| D        | 4.80                      | 5.20  | 5.30  | 0.201                | 0.205 | 0.209 |
| D1       | 4.25                      | 4.35  | 4.45  | 0.167                | 0.171 | 0.175 |
| E        | 5.45                      | 5.55  | 5.65  | 0.215                | 0.219 | 0.222 |
| E1       | 5.95                      | 6.05  | 6.15  | 0.234                | 0.238 | 0.242 |
| E2       | 3.525                     | 3.625 | 3.725 | 0.139                | 0.143 | 0.147 |
| E3       | 1.175                     | 1.275 | 1.375 | 0.046                | 0.050 | 0.054 |
| e        | 1.27 BSC                  |       |       | 0.050 BSC            |       |       |
| L        | 0.45                      | 0.55  | 0.65  | 0.018                | 0.022 | 0.026 |
| L1       | 0                         | ---   | 0.15  | 0                    | ---   | 0.006 |
| L2       | 0.68 REF                  |       |       | 0.027 REF            |       |       |
| $\theta$ | 0°                        | ---   | 10°   | 0°                   | ---   | 10°   |

NOTE

UNIT: mm

- PACKAGE BODY SIZES EXCLUDE MOLD FLASH AND GATE BURRS.  
MOLD FLASH AT THE NON-LEAD SIDES SHOULD BE LESS THAN 6 MILS EACH.
- CONTROLLING DIMENSION IS MILLIMETER.  
CONVERTED INCH DIMENSIONS ARE NOT NECESSARILY EXACT.

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